

Integrated Device Technology, Inc. 6024 Silver Creek Valley Road, San Jose, CA - 95138

WIDI.	TM	COCESS CHANGE NOTICE (PCN)
PCN #: A1304-01 Product Affected:	Date: April 29, LDS6120PVGI, LDS6120PVGI built in SSOP-48	Back Mark Lot # will have "P" prefix □ Back Mark □ Date Code
Date Effective:	July 29, 2013	□ Other
	ot PCN DESK cndesk@idt.com	Attachment: Yes No Samples: Samples are available now.
DESCRIPTION AN ☐ Die Technology ☐ Wafer Fabrication ☐ Assembly Process ☐ Equipment ☐ Material ☐ Testing ■ Manufacturing Si ☐ Data Sheet ☐ Other	s	This notification is to advise our customers that IDT is adding Amkor, Philippines (ATP) as an alternate assembly facility for device type LDS6120PVGI and LDS6120PVGI8. Presently, ATP is a qualified assembly facility for SSOP package family. There is no change to the moisture performance.
_	JALIFICATION SUMMARY: I change to the product quality and	I reliability.
IDT records indicate to grant approval or it will be assumed the IDT reserves the rig	request additional information. If hat this change is acceptable.	PT: ion of this change. Please use the acknowledgement below or E-Mail IDT does not receive acknowledgement within 30 days of this notice ured after the process change effective date until the inventory
Customer:		☐ Approval for shipments prior to effective date.
Name/Date:	E-	Mail Address:
Title:	Ph	none# /Fax# :
CUSTOMER COM	IMENTS:	
IDT ACKNOWLE	DGMENT OF RECEIPT:	
RECD. BY:		DATE:



PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT 1 - PCN # : A1304-01

PCN Type: Alternate Assembly Location

Data Sheet Change: None. No change in moisture sensitivity level (MSL).

Detail Of Change:

This notification is to advise our customers that IDT is adding Amkor, Philippines (ATP) as an alternate assembly facility for device types LDS6120PVGI and LDS6120PVGI8. Presently, ATP is a qualified assembly facility for SSOP package family.

The material set details of the current Assembly location is shown in the table below. The die attach used at ATP is qualified IDT material. There is no change from the existing qualified lead frame material, lead finish, mold compound and wire for this alternate assembly site.

There is no change to the moisture performance using the assembly material sets as listed in the below table.

Qualified Material Sets, by Assembly Subcontractor

Description	Existing	Add		
Assembly Location	PT Unisem, Indonesia	Amkor, Philippines		
	Die Attach: CRM1076NS	Ablestik 8290		
	Wire: Au Wire	Au Wire		
Assembly Materials	Mold Compound: G600	G600		
	Lead Frame: Copper Alloy	Copper Alloy		
	Plating: Matte 100% Sn	Matte 100% Sn		



PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT 1 - PCN # : A1304-01

Qualification Information and Qualification Data:

Qualification Test Plans and Results:

Qual Plan & Results: The qualification was performed in accordance with JEDEC47 recommended

tests

Qual Vehicle: Device 9P946AFLF SSOP-48 (3 lots)

		Test Results (SS / Rej)		
Test Description	Test Method	Lot 1	Lot 2	Lot 3
* HAST - biased (130 °C/85% RH, 100 Hrs)	JESD22-A110	25/0	25/0	25/0
* Temperature Cycle / Condition B (-55 °C to +125 °C, 700 Cyc)	JESD22-A104	25/0	25/0	25/0
* Pressure Cooker (121°C / 2 ATM, 168 hours)	JESD22-A102	25/0	25/0	25/0
High Temp. Storage Test (150 °C, 1000 Hrs)	JESD22-A103	25/0	25/0	25/0

Note:

^{*} Test requires moisture pre-conditioning sequence per JESD22-A113 prior to stress test